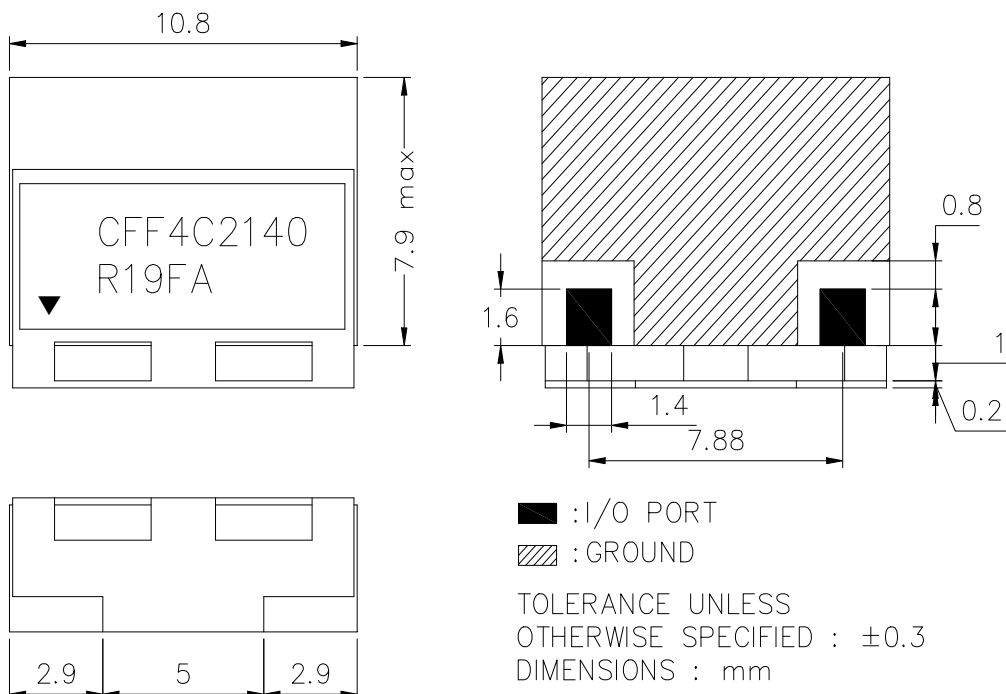


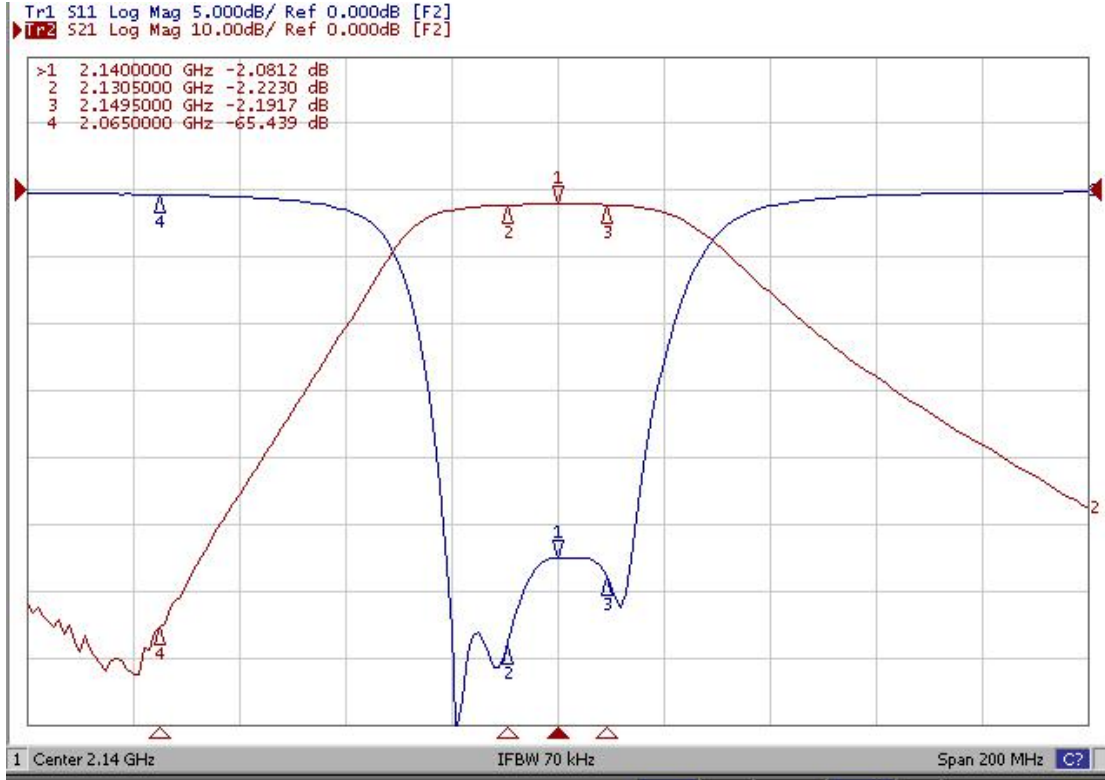
**Electrical Specification**

ITEMS	SPEC	UNIT
Center Frequency [fo]	2140	MHz
Bandwidth [BW]	fo ±9.5 [2130.5~2149.5]	MHz
Insertion Loss in BW	2.5	dB max
Ripple in BW	0.5	dB max
Return Loss in BW	18.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	50dB min @ fo ± [ 2065 ]	MHz
	dB min @ fo ± [ ~ ]	MHz
	dB min @ fo ± [ ~ ]	MHz
	dB min @ fo ± [ ~ ]	MHz
Group Delay Variation		ns max
Input Power	2	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

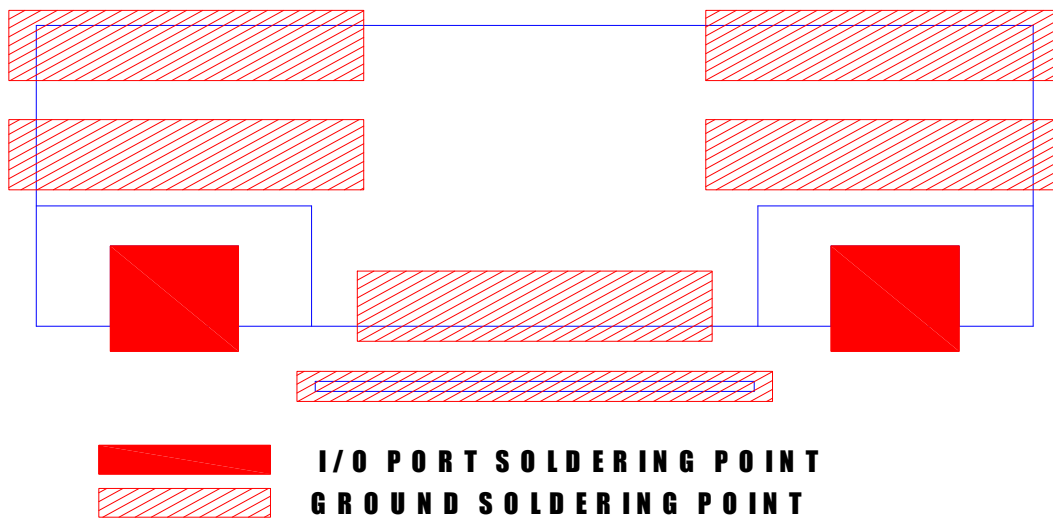
**Mechanical Specification**



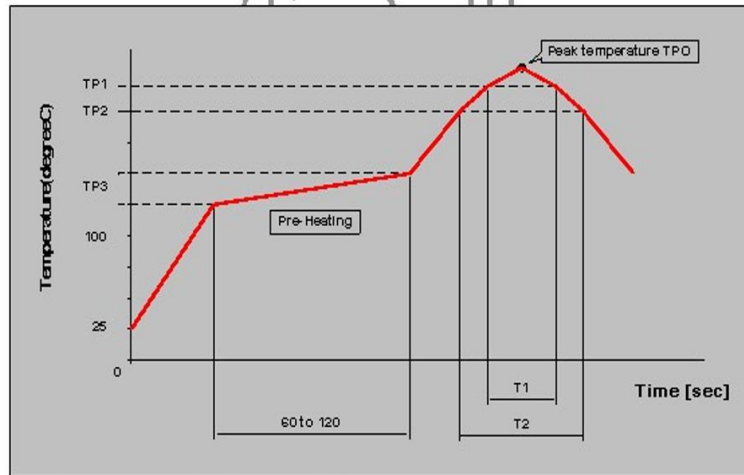
**Plot Data**



**Recommned PC Board Pattern**



 **Soldering Condition**



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180